DS04-13513-1E

Linear IC Converter CMOS D/A Converter for Digital Tuning (12-channel, 8-bit, on-chip OP amp., low-voltage)

MB88146A

DESCRIPTION

The MB88146A is an 8-bit D/A converter with twelve built-in channels. The 12 analog outputs each have a builtin OP amplifier with large current drive-capability.

The data input/output format is CS (chip select) with serial bus connection available.

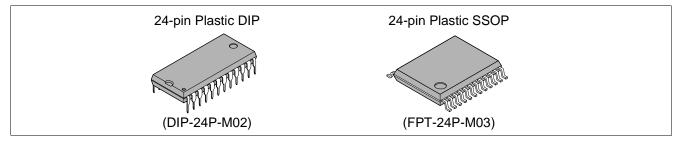
A built-in 12-bit I/O expander enables serial \leftrightarrow parallel conversion (8 of the 12 bits can also be used for analog output).

This product can be used for microcontroller port expansion, electronic level adjustment, replacement of semifixed resistance for tuning, etc.

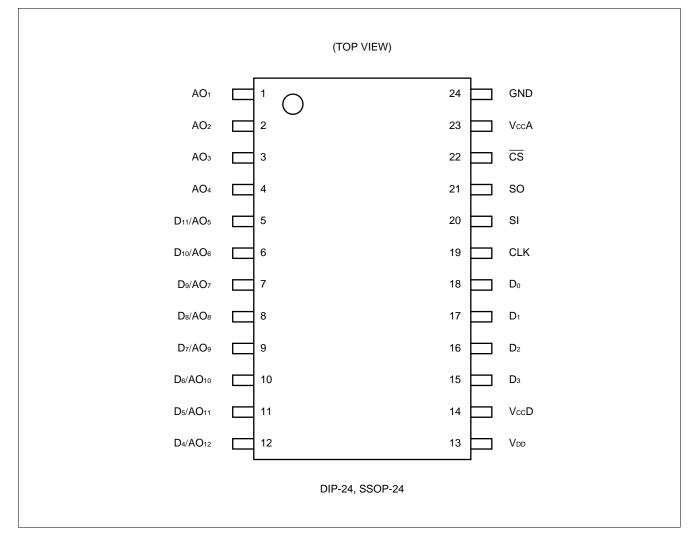
■ FEATURES

- Ultra low power consumption (1.2 mW/chl: typical)
- Ultra compact package
- Built-in 12-channel R-2R type 8-bit D/A converter
- Built-in 12-bit I/O expander (8 bits also function as analog output)
- Built-in analog output amplifier (sink current 1.0 mA maximum, source current 1.0 mA maximum)
- Built-in power-on detection circuit (initialized at detection of VccD power-on)
- MCU interface compatible with 3 V to 5 V systems
- Power divided into MCU interface power supply (VccD) and OP amplifier power supply (VccA), D/A converter power supply (VccD)
- Analog output capability from 0 V to VccA
- Serial data I/O operates to maximum of 2.5 MHz (in cascade connection, up to 2.5 MHz when VccD = 5 V, up to 1.5 MHz when VccD = 3 V)
- CMOS process
- Choice of two packages: SDIP-24 pin and SSOP-24 pin.

PACKAGES



■ PIN ASSIGNMENT

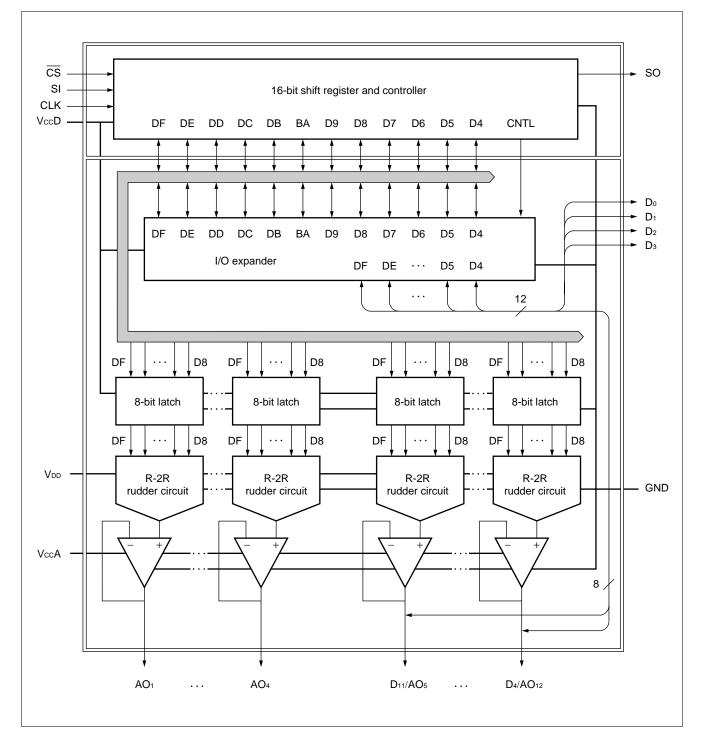


■ PIN DESCRIPTION

Pin no.	Pin name	Description
1 to 4	AO ₁ to AO ₄	D/A converter analog output pins (VDD to GND output). (Default: output #00 setting level)
5 to 12	D ₁₁ /AO ₅ to D ₄ /AO ₁₂	These pins may be used either as I/O expander parallel input/output (V _{CC} A/ GND output 0.5 V _{CC} A/0.2 V _{CC} A input) or D/A converter analog output (V _{DD} to GND output). Pin status is controlled by input data. See "■Data Configuration". (Default: Input mode, Hi-Z state)
13	Vdd*1	D/A converter reference power pin.
14	VccD*1	MCU interface power supply pin (power supply for I/O expander).
15 to 18	D ₃ toD ₀	 I/O expander parallel input/output pins. (VccD/GND output: When VccD ≥ 4.0 V, 0.5 VccD/0.2 VccD input, When VccD < 4.0 V, 2 V/0.2 VccD input) Pin status is controlled by input data. See "■Data Configuration." (Default: Input mode, Hi-Z state)
19	CLK*2	Shift clock signal input pin. When \overline{CS} = "L," SI data is loaded into the shift register at the rising edge of the shift clock.
20	SI *2	Data input pin (serial input pin). Used for 16-bit serial data input.
21	SO	Data output pin (serial output pin). The first bit (LSB) data of the 16-bit shift register is output simultaneously with the falling edge of the shift clock. When CS output = "H," this pin goes to high impedance state.
22	CS*2	Chip select signal input pin. Input to shift registers is enabled when the \overline{CS} signal falling edges. Shift register contents can be executed when the \overline{CS} signal rising edges.
23	VccA*1	Analog unit power supply pin (OP amplifier power supply).
24	GND	Common GND pin.

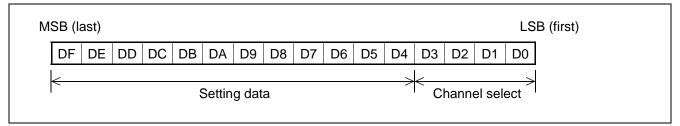
*1: Be sure that VccA \geq VccD, and that VccA \geq VDD. *2: Do not leave this pin in floating state.

■ BLOCK DIAGRAM



■ DATA CONFIGURATION

1. Data Configuration



2. Channel Select

D3	D2	D1	D0	Function
0	0	0	0	Don't Care/special function
0	0	0	1	AO ₁ selected
0	0	1	0	AO ₂ selected
to	to	to	to	to
1	0	1	1	AO11 selected
1	1	0	0	AO ₁₂ selected
1	1	0	1	I/O expander (serial \rightarrow parallel)
1	1	1	0	I/O expander (parallel \rightarrow serial)
1	1	1	1	Expander status register (ESR)

3. Setting Data

DF	DE	DD	DC	DB	DA	D9	D8	D7	D6	D5	D4	Analog output voltage level
×	×	×	×	×	×	×	×	0	0	0	0	Don't Care
to	Don't Care											
×	×	×	×	×	×	×	×	1	0	1	1	Don't Care
0	0	0	0	0	0	0	0	1	1	0	0	GND (all channels)
0	0	0	0	0	0	0	1	1	1	0	0	$V_{DD}/256 \times 1$ (all channels)
0	0	0	0	0	0	1	0	1	1	0	0	$V_{DD}/256 \times 2$ (all channels)
to												
1	1	1	1	1	1	1	0	1	1	0	0	$V_{DD}/256 \times 254$ (all channels)
1	1	1	1	1	1	1	1	1	1	0	0	$V_{DD}/256 \times 255$ (all channels)
×	×	×	×	×	×	×	×	1	1	0	1	Hi-Z (I/O expander state)*
×	×	×	×	×	×	×	×	1	1	1	0	Reset (state when power is ON)
×	×	×	×	×	×	×	×	1	1	1	1	Don't Care

• Don't Care/special function (Channel select = "0000")

×: Don't care *: Hi-Z output on all channels of AO5 through AO12

DF	DE	DD	DC	DB	DA	D9	D8	D7	D6	D5	D4	Analog output voltage level
0	0	0	0	0	0	0	0	0	0	0	0	GND
0	0	0	0	0	0	0	1	0	0	0	0	$V_{DD}/256 imes 1$
0	0	0	0	0	0	1	0	0	0	0	0	$VDD/256 \times 2$
0	0	0	0	0	0	1	1	0	0	0	0	$V_{DD}/256 imes 3$
to												
1	1	1	1	1	1	0	1	0	0	0	0	$V_{DD}/256 \times 253$
1	1	1	1	1	1	1	0	0	0	0	0	Vdd/256 × 254
1	1	1	1	1	1	1	1	0	0	0	0	$V_{DD}/256 \times 255$
×	Х	×	×	×	×	×	×	0	0	0	1	Hi-Z (I/O expander state)*
×	×	×	×	×	×	×	×	0	0	1	0	Don't Care
to	Don't Care											
×	×	×	×	×	×	×	×	1	1	1	1	Don't Care

• D/A Converter (Channel select = "0001" to "1100")

 \times : Don't care *: Only AO₅ through AO₁₂ output is valid

• I/O Expander [Channel select = "1101"]: Serial \rightarrow Parallel Conversion

Performs parallel conversion of data bits D4 to DF for output on pins D₀ to D₁₁. Note that only those pins designated for output in the ESR (expander status register) are output.

Shift register

DF	DE	DD	DC	DB	DA	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	\Rightarrow
\downarrow	\downarrow	\downarrow	\downarrow	\downarrow	\downarrow	\downarrow	\downarrow	\downarrow	\downarrow	\downarrow	\downarrow					-
D 11	D 10	D9	D8	D7	D ₆	D₅	D4	Dз	D ₂	D1	D ₀	Para	allel I	/O pir	าร (อเ	utput state)

• I/O Expander [Channel select = "1110"]: Parallel \rightarrow Serial Conversion

Writes data from Do to D11 pins to bits D4 to DF in the shift register.

Data is output to the SO pin on the shift clock (CLK) signal (The first 4 bits output data D0 to D3, so the converted output should be read as data bits 5 through 16.).

Note that the data value is "0" for pins designated for output in the ESR (expander status register) as well as analog output pins.

Shift register

DF	DE	DD	DC	DB	DA	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	
\uparrow	\uparrow	\uparrow	\uparrow	\uparrow	\uparrow	\uparrow	\uparrow	\uparrow	\uparrow	\uparrow	\uparrow					
D11	D 10	D9	D8	D7	D ₆	D₅	D4	D₃	D ₂	D1	Do	Para	allel I/	O pin	s (ou	tput state)

• Expander Status Register [Channel select = "1111"]

Shift register

DF	DE	DD	DC	DB	DA	D9	D8	D7	D6	D5	D4	ESR
\downarrow												
D11	D 10	D۹	D8	D7	D6	D5	D4	Dз	D2	D1	Do	

This register sets the status of each pin.

Setting	Pin status
"O"	 Input standby status (Hi-Z output) D₁₁ to D₄ pins used for analog output should be set to "0."
"1"	Output state

Note: After power VccD is turned on, the state of pins and registers is as follows.

Pin	State
AO1 to AO4	"L" output
D11/AO5 to D4/AO12	Hi-Z state (input state)
D ₃ to D ₀	Hi-Z state (input state)

Register	State
Shift register	Bits DF to D8 are "0," and D7 to D0 are not defined (retain prior state).
D/A register	All reset to "0."
Parallel output register	Not defined (retain prior state).
Expander status register (ESR)	All reset to "0."

• ESR settings have priority in determining pin states. Switching between input standby state and analog output state is enabled even when the ESR value is "1." When the ESR value returns to "0", the pin returns to its previously defined state.

• In input standby state with AO set for Hi-Z output, the AO output setting can be used for transition to AO output state.

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Conditions	Ra	ting	Unit
Parameter	Symbol	Conditions	Min.	n. Max.	
	VccA		-0.3	+7.0	V
Power supply voltage	VccD	Based on GND (Ta = +25°C)	-0.3	VccA*	V
	Vdd	(14 120 0)	-0.3	VccA*	V
Input voltage 1	Vin1	SI, CLK, CS ,	-0.3	VccD + 0.3	V
Output voltage 1	Vout1	SO, D ₀ to D ₃	-0.3	VccD + 0.3	V
Input voltage 2	Vin2	D4 to D11	-0.3	VccA + 0.3	V
Output voltage 2	Vout2	D4 10 D11	-0.3	VccA + 0.3	V
Power consumption	PD	—	—	250	mW
Operating temperature	Та	_	-20	+85	°C
Storage temperature	Tstg	—	-55	+150	°C

* : VccA \geq VccD, VccA \geq Vdd

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING CONDITIONS

Deremeter	Symbol	Conditions		Value		l Init
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
	VccA	—	4.5	5.0	5.5	V
Dower oupply veltage	VccD	$VccA \geqq VccD$	2.7	—	VccA	V
Power supply voltage	Vdd	$V_CCA \geqq V_DD$	2.0	—	VccA	V
	GND	—		0		V
	Ial	Source current			1.0	mA
Analog output current	Іан	Sink current			1.0	mA
Oscillation limit output capacity	Сог		—	_	1.0	μF
Operation temperature	Та		-20		+85	°C

WARNING: Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representative beforehand.

■ ELECTRICAL CHARACTERISTIC

1. DC Characteristics

(1) Digital section

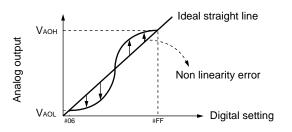
Baramatar	Symbol	Din nomo	Conditions		Value		
Parameter	Symbol	Pin name	Conditions	Min.	Тур.	Max.	Unit
Power supply voltage	VccD		—	2.7	5.0	5.5	V
Power supply current	IccD	VccD	CLK =1 MHz, (Unloaded)	—	0.2	0.5	mA
Standby current	IccS	VOOD	CLK, SI, CS Stop V _{in} = V _{CC} D or GND	-10		+10	μΑ
Input leak current	IILK1		V _{in} = 0 to VccD	-10	—	+10	μA
"H" level input voltage	V _{IH1}	C <u>LK,</u> SI, CS,	$VccD \ge 4.0 V$	0.5 imes VccD		—	V
TT level input voltage	V IH1	D₀ to D₃	VccD < 4.0 V	2.0		_	V
"L" level input voltage	VIL1		_		_	0.2 imes VccD	V
High-impedance leak current	Іоік	SO	V _{in} = 0 to VccD	-10	_	+10	μA
"H" level output voltage	Vон1	SO,	Iон = -0.4 mA	VccD-0.4	_	_	V
"L" level output voltage	Vol1	D ₀ to D ₃	lo∟ = 2.5 mA	—	—	0.4	V

(VccD \leq VccA, Ta = –20°C to +85°C)

(2) D/A converter section

Deremeter	Symbol	Din nomo	Conditions		Value		l Init
Parameter	Symbol	Pin name	Conditions	Min.	Тур.	Max.	Unit
Power supply voltage	Vdd	Vdd	$V_{DD} \leqq V_{CC}A$	2.0	5.0	5.5	V
Power supply current	ldd		$V_{DD} \leqq V_{CC}A$		1.2	2.5	mA
Resolution	Res		Unload		8		bits
Monotonic increase	Rem		$V_{DD} = V_{CC}A - 0.1 V$		8	_	bits
Nonlinearity error	LE		Digital value: #06	-1.5		+1.5	LSB
Differential linearity error	DLE		to #FF	-1.0	—	+1.0	LSB

Nonlinearity error:	Deviation (error) in input/output curves with respect to an ideal straight line connecting output voltage at "06" and output voltage at "FF."
Differential linearity error:	Deviation (error) in amplification with respect to theoretical increase in amplification per 1-bit increase in digital value.



Note: The value of V_{AOH} and V_{DD}, and the value of V_{AOL} and GND are not necessarily equivalent.

(3) Operational Amplifier/Analog output section

 $(V_{DD} = V_{CC}A = 5.0 \text{ V}, \text{ Ta} = -20^{\circ}\text{C to } +85^{\circ}\text{C})$

Deversion	Cumb al		Conditions		Value		Unit
Parameter	Symbol	Pin name	Conditions	Min.	Тур.	Max.	Unit
Power supply voltage	Vcca			4.5	5.0	5.5	V
Power supply current	Ісса	VccA	#80 setting (Unloaded)	—	1.0	3.7	mA
Input leak current	IILK2		V _{in} = 0 to V _{cc} A	-10		+10	μΑ
"H" level digital input voltage	VIH2		—	0.5 imes VccA	—	_	V
"L" level digital input voltage	VIL2	D4 to D11	_	—	_	$0.2 \times VccA$	V
"H" level digital output voltage	Vон2	-	Іон = -0.4 mA	VccA-0.4	_	_	V
"L" level digital output voltage	Vol2		lo∟ = 2.5 mA	—	_	0.4	V
Analog output minimum voltage 1	VAOL1		I _{AL} = 0 A #00 setting	GND	—	0.1	V
Analog output minimum voltage 2	VAOL2		I _{AL} = 0.5 mA #00 setting	-0.2	GND	0.2	V
Analog output minimum voltage 3	Vaol3	AO1 to AO12	I _{AH} = 0.5 mA #00 setting	GND	_	0.2	V
Analog output minimum voltage 4	VAOL4		I _{AL} = 1.0 mA #00 setting	-0.3	GND	0.3	V
Analog output minimum voltage 5	VAOL5		I _{AH} = 1.0 mA #00 setting	GND	_	0.3	V
Analog output maximum voltage 1	Vaoh1		I _{AL} = 0 A #FF setting	VccA-0.1	—	VccA	V
Analog output maximum voltage 2	Vaoh2		I _{AL} = 0.5 mA #FF setting	VccA-0.2	—	VccA	V
Analog output maximum voltage 3	Vаонз	AO1 to AO12	I _{AH} = 0.5 mA #FF setting	VccA-0.2	VccA	VccA+0.2	V
Analog output maximum voltage 4	Vаон4		I _{AL} = 1.0 mA #FF setting	VccA-0.3	_	VccA	V
Analog output maximum voltage 5	Vaoh5		I _{AH} = 1.0 mA #FF setting	VccA-0.3	VccA	VccA+0.3	V

Note: IAH: Analog output sink current IAL: Analog output source current

2. AC Characteristics

• For operation at VccD = 5.0 V

(VDD =	VccA =	50V	Ta =	-20°C	$t_{0} + 85^{\circ}$	°C)
	v DD -	V CC/ (-	0.0 v,	iu –	200	10 100	$\mathcal{O}_{\mathcal{I}}$

Deveryor	Cumb al	Conditions		Value		11
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Clock "L" level pulse width	t cĸ∟	—	200	_	_	ns
Clock "H" level pulse width	tскн	—	200			ns
Clock rise time	t Cr	—	_	_	200	ns
Clock fall time	tcf	—	_	_	200	ns
Serial input setup time	t ssu	—	30	_	—	ns
Serial input hold time	t shd	—	60	_	—	ns
Serial output delay time	tsod	See "Load condition 1"	0	80	170	ns
CS input setup time	t csu	—	100	_	—	ns
CS hold time	t ссн	—	200			ns
CS "H" level hold time	tсsн	—	100	_	—	ns
Data output enable time	tso	—		_	200	ns
Data output float time	t soz	—			200	ns
Parallel input setup time	t PSU	—	30	_	_	ns
Parallel input hold time	t PHD	—	60	_		ns
Parallel output delay time	t POD	See "Load condition 1"	_	100	170	ns
Analog output delay time	taod	See "Load condition 2"	_	30	100	μs
Power supply rise time	tR	—	_		50	ms
Power-on reset non-startup power supply variation	ΔV_{R}	_	-10		10	V/µs

For operation at VccD = 3.0 V *1

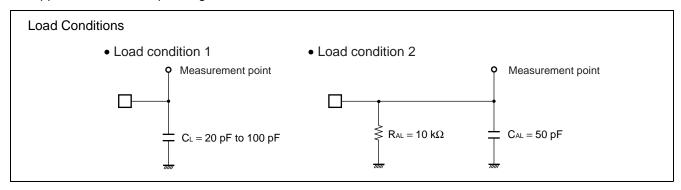
 $(VccD = 3.0 V, Ta = -20^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Conditions	Value			Unit	
Farameter	Symbol	Conditions	Min.	lin. Typ. Max.			
Serial output delay time	tsod	See "Load condition 1"*2	0	120	300	ns	
Parallel output delay time	t POD	See "Load condition 2"*3	—	120	300	ns	

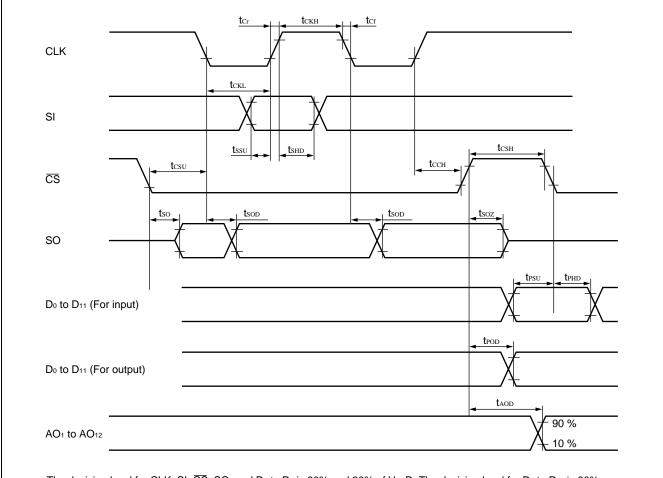
*1: Items not listed are identical to characteristics for VccD = 5.0 V.

*2: Cascade connection enabled at 1.5 MHz.

*3: Applied to D0 to D3 operating at VccD.



• Input/Output Timing (CS method)



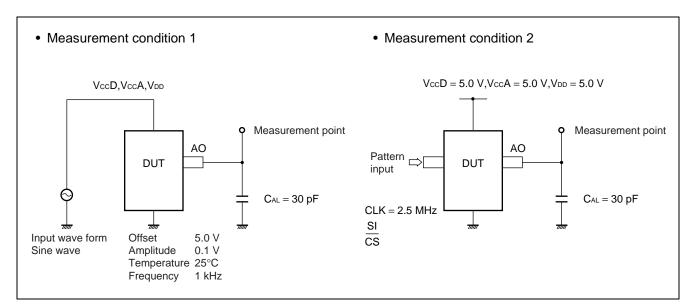
The decision level for CLK, SI, \overline{CS} , SO, and D₀ to D₃ is 80% and 20% of V_{Cc}D. The decision level for D₄ to D₁₁ is 80% and 20% of V_{Cc}A, and for AO₁ to AO₁₂ is 90% and 10% of V_{Cc}A.

• Power Supply Timing

Power-On Timing		
VccD	2.0 V 0.2 V	
Power-On Reset Non-Stat	rtup Supply Variation	
Upper limit, 5.5V		
VccD		$\Delta V_{R} = \frac{\Delta V}{\Delta T}$
2.7V, lower limit		

3. Analog Output Noise Characteristic

 $(V_{DD} = V_{CC}D = V_{CC}A = 5.0 \text{ V}, \text{ Ta} = +25^{\circ}\text{C})$ Value Measurement Symbol Parameter Conditions Unit condition Min. Тур. Max. Digital supply noise PSRD $f_{\text{NOISE}} = 1 \text{ kHz}$ 1 20 dB reduction ratio Analog supply noise 1 PSRA $f_{NOISE} = 1 \text{ kHz}$ 20 dB reduction ratio D/A supply noise 1 PSRDA $f_{NOISE} = 1 \text{ kHz}$ 0 dB reduction ratio • During serial transfer During analog operation Operating noise V_{N1} 2 -30 30 mV • During Hi-Z commands. See "Operating Noise V_{N1}." • Serial \rightarrow parallel conversion See "I/O Expander Operating Noise 1 V_{N2}." During digital-only pin operation I/O expander operating V_{N2} 2 -3030 mV noise 1 • During parallel \rightarrow serial conversion • ESR setting During digital input/digital output switching • During serial \rightarrow parallel conversion See "I/O Expander Operating Noise 2 V_{N3}." During digital/analog capable pin I/O expander operating V V_{N3} 2 -0.10.1 noise 2 operation • ESR setting During digital output/digital output switching

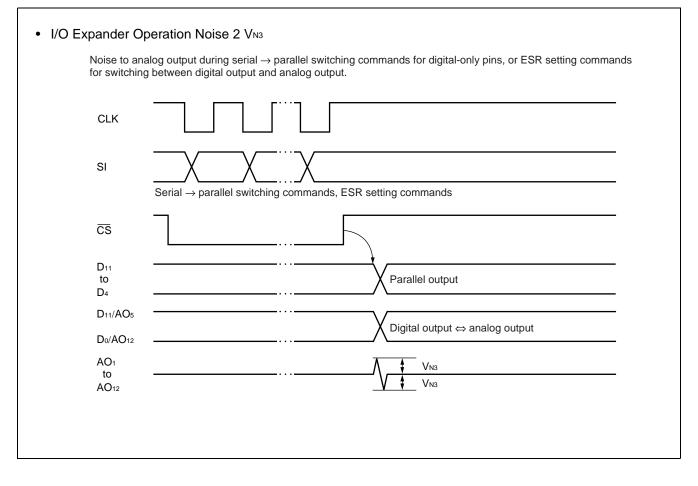


Analog Output Noise Description

Noise to a	analog output during serial data transfer, analog operation, Hi-Z commands.
CLK	
SI	Analog operation commands, Hi-Z commands
ĊS	
AO×	Analog output
D11/AO5 to D0/AO12	 Digital input* ⇔ analog output
AO ₁ to AO ₁₂	
1012	
	te = digital input state.
* Hi-Z sta	
* Hi-Z sta Expander C Noise to a	te = digital input state. Operation Noise 1 V _{N2} analog output during parallel \rightarrow serial conversion commands, serial \rightarrow parallel conversion command for y pins, or ESR setting commands for switching between digital input and digital output.
* Hi-Z sta Expander C Noise to a	Dperation Noise 1 V _{N2} analog output during parallel \rightarrow serial conversion commands, serial \rightarrow parallel conversion command for
* Hi-Z sta Expander C Noise to a digital-on	Deperation Noise 1 V _{N2} analog output during parallel \rightarrow serial conversion commands, serial \rightarrow parallel conversion command for y pins, or ESR setting commands for switching between digital input and digital output.
* Hi-Z sta Expander C Noise to a digital-on CLK	Dperation Noise 1 V _{N2} analog output during parallel \rightarrow serial conversion commands, serial \rightarrow parallel conversion command for
* Hi-Z sta Expander C Noise to a digital-on CLK	Deperation Noise 1 V _{N2} analog output during parallel \rightarrow serial conversion commands, serial \rightarrow parallel conversion command for y pins, or ESR setting commands for switching between digital input and digital output.
* Hi-Z sta Expander C Noise to a digital-on CLK SI	Deperation Noise 1 V _{N2} analog output during parallel \rightarrow serial conversion commands, serial \rightarrow parallel conversion command for y pins, or ESR setting commands for switching between digital input and digital output.
* Hi-Z sta Expander C Noise to a digital-on CLK SI CS D3 to D0	Deperation Noise 1 V _{N2} analog output during parallel \rightarrow serial conversion commands, serial \rightarrow parallel conversion command for y pins, or ESR setting commands for switching between digital input and digital output.
* Hi-Z sta Expander C Noise to a digital-on CLK SI CS D3 to	Deperation Noise 1 V _{N2} analog output during parallel \rightarrow serial conversion commands, serial \rightarrow parallel conversion command for y pins, or ESR setting commands for switching between digital input and digital output.



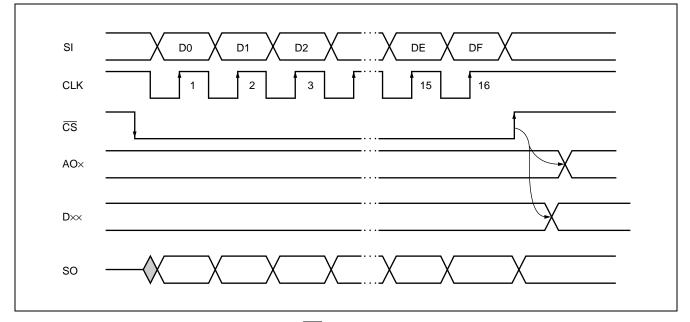
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■ DATA INPUT/OUTPUT TIMING

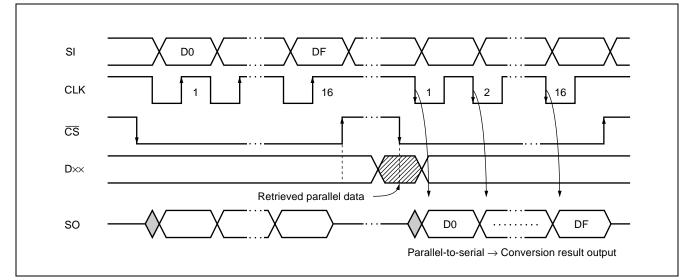
MB88146A Data Input/Output Timing (Serial Bus Format)

• D/A converter operation, and I/O expander (serial \rightarrow parallel conversion) operation, and ESR writing operation.



Data input is enabled at the falling edge of the \overline{CS} signal. 16-bit data is input, and the shift register command is executed at the rising edge of \overline{CS} .

In D/A converter operation, the analog output selected at the rising edge of \overline{CS} is the conversion result. In serial \rightarrow parallel conversion, the digital output selected at the rising edge of \overline{CS} is the conversion result. In ESR write operation, ESR data is set and pin status determined at the rising edge of \overline{CS} .



- I/O expander (parallel \rightarrow serial conversion) operation

Data input is enabled at the falling edge of the \overline{CS} signal. 16-bit data (parallel \rightarrow serial conversion commands) is input and commands accepted at the rising edge of \overline{CS} . At the falling edge of \overline{CS} , data from the parallel input is loaded into bits D4 to DF of the shift register, and output from the SO pin timed to the falling edge of the CLK signal.

■ USAGE PRECAUTIONS

1. Preventing Latch-Up

A condition known as "latch-up" may occur when the input or output pins of a CMOS IC device are exposed to voltages higher then V_{CC}D or V_{CC}A or lower than GND voltage, or when voltages are applied to the device in excess of rated values for V_{CC}D, V_{CC}A, or V_{DD} to GND voltages. Latchup produces a rapid increase in power supply current, and may result in thermal destruction of elements. Users should take sufficient precautions to ensure that absolute maximum ratings are not exceeded at any time during use.

2. Power Supply Pins

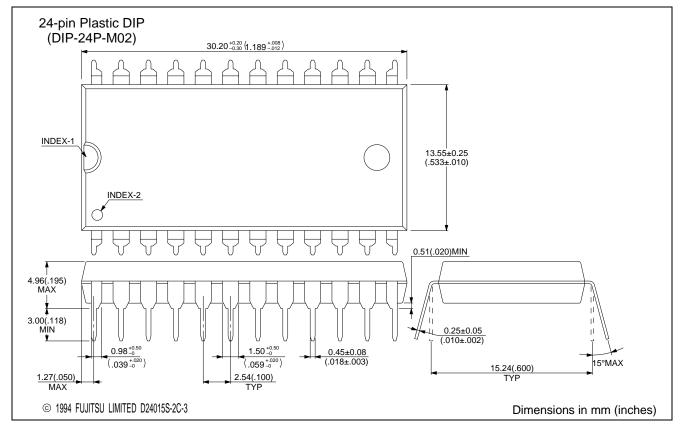
The power supply should be connected to the VccD, VccA, VDD, and GND terminals of the MB88146A with as low an impedance as possible.

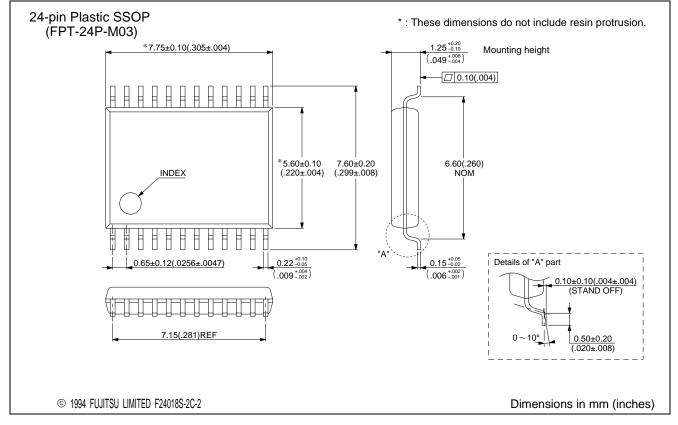
In addition, it is recommended that ceramic capacitors or approximately 0.1 μ F be connected as bypass capacitors between the V_{CC}D, V_{CC}A, and V_{DD} terminals and the GND terminals.

ORDERING INFORMATION

Part number	Package	Remarks
MB88146AP	24-pin Plastic DIP (DIP-24P-M02)	
MB88146APFV	24-pin Plastic SSOP (FPT-24P-M03)	

PACKAGE DIMENSIONS





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